NOTES:
2. DIMENSION IN MILLIMETERS, ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.

---

<table>
<thead>
<tr>
<th>DIM</th>
<th>MIN</th>
<th>NOM</th>
<th>MAX</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>1.35</td>
<td>1.55</td>
<td>1.75</td>
</tr>
<tr>
<td>A1</td>
<td>0.00</td>
<td>0.05</td>
<td>0.10</td>
</tr>
<tr>
<td>A2</td>
<td>1.35</td>
<td>1.50</td>
<td>1.65</td>
</tr>
<tr>
<td>b</td>
<td>0.35</td>
<td>0.42</td>
<td>0.49</td>
</tr>
<tr>
<td>c</td>
<td>0.19</td>
<td>0.22</td>
<td>0.25</td>
</tr>
<tr>
<td>D</td>
<td>9.90BSC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>E</td>
<td>6.00BSC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>E1</td>
<td>3.90BSC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>e</td>
<td>1.27BSC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>h</td>
<td>0.25</td>
<td>---</td>
<td>0.50</td>
</tr>
<tr>
<td>L</td>
<td>0.40</td>
<td>0.83</td>
<td>1.25</td>
</tr>
<tr>
<td>L1</td>
<td>1.05REF</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

TOLERANCE OF FORM AND POSITION:

- aaa: 0.10
- bbb: 0.20
- ccc: 0.10
- ddd: 0.25
- eee: 0.10

**MILLIMETERS**

**DETAIL "A"**

**SIDE VIEW**

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**RECOMMENDED MOUNTING FOOTPRINT**

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, soldering/...*
SOIC−16 9.90x3.90x1.50 1.27P
CASE 751B
ISSUE L

DATE 29 MAY 2024

**GENERIC MARKING DIAGRAM**

![Generic Marking Diagram]

**style 1:**
1. COLLECTOR
2. BASE
3. EMITTER
4. NO CONNECTION
5. EMITTER
6. BASE
7. COLLECTOR
8. COLLECTOR
9. BASE
10. EMITTER
11. NO CONNECTION
12. EMITTER
13. BASE
14. COLLECTOR
15. EMITTER
16. COLLECTOR

**style 2:**
1. CATHODE
2. ANODE
3. NO CONNECTION
4. CATHODE
5. CATHODE
6. NO CONNECTION
7. ANODE
8. CATHODE
9. CATHODE
10. ANODE
11. NO CONNECTION
12. CATHODE
13. CATHODE
14. NO CONNECTION
15. ANODE
16. CATHODE

**style 3:**
1. COLLECTOR, DYE #1
2. BASE, #1
3. EMITTER, #1
4. COLLECTOR, #1
5. COLLECTOR, #2
6. BASE, #2
7. EMITTER, #2
8. COLLECTOR, #2
9. COLLECTOR, #3
10. BASE, #3
11. EMITTER, #3
12. COLLECTOR, #3
13. COLLECTOR, #4
14. BASE, #4
15. EMITTER, #4
16. BASE, #1

**style 4:**
1. COLLECTOR, DYE #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. COLLECTOR, #3
6. COLLECTOR, #3
7. COLLECTOR, #4
8. COLLECTOR, #4
9. BASE, #4
10. EMITTER, #4
11. BASE, #3
12. EMITTER, #3
13. BASE, #2
14. EMITTER, #2
15. BASE, #1
16. EMITTER, #1

**style 5:**
1. DRAIN, DYE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. DRAIN, #3
6. DRAIN, #3
7. DRAIN, #4
8. DRAIN, #4
9. GATE, #4
10. GATE, #4
11. GATE, #3
12. GATE, #3
13. GATE, #2
14. GATE, #2
15. SOURCE, #2
16. SOURCE, #2

**style 6:**
1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. CATHODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE
15. ANODE
16. ANODE

**style 7:**
1. SOURCE N−CH
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. CATHODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE
15. ANODE
16. ANODE

**XXXXXXXX = Specific Device Code**
**A = Assembly Location**
**WL = Wafer Lot**
**Y = Year**
**WW = Work Week**
**G = Pb−Free Package**

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “/C0071”, may or may not be present. Some products may not follow the Generic Marking.